

REMOVABLE ADHESIVE SHEET FOR SEMICONDUCTOR PROCESSING

5 [Abstract]

A removable adhesive sheet for semiconductor processing, containing a removable adhesive layer provided on a base material film, in which a 5 percent modulus of the base material film is 7.0 to 20.0 MPa; the base material film is single-layered, and contains 5 to 39 mass parts of a styrene-based block
10 copolymer with respect to 100 mass parts of a base resin; the styrene-based block copolymer is at least one kind of resin selected from the group consisting of a styrene-hydrogenated isoprene-styrene block copolymer, a styrene-isoprene-styrene block copolymer, a styrene-hydrogenated butadiene-styrene block
15 copolymer, and a styrene-hydrogenated isoprene/butadiene-styrene block copolymer; and the base resin is at least one kind of resin selected from specific resins such as a polypropylene, a polyethylene, and the like.

[Fig. 1]